## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

| Application of: Bleys et al. | §           | Confirmation No.: 8094     |
|------------------------------|-------------|----------------------------|
| Serial No.: 09/914,537       | §<br>§      | Art Unit: 1796             |
| Filed: December 13, 2001     | §<br>§<br>§ | Examiner: Rabon A. Sergent |

Title: Process for Preparing Moulded Polyurethane Material

## RULE 1.132 DECLARATION OF HANS GODELIEVE GUIDO VERBEKE

I, Hans Godelieve Guido VERBEKE, the undersigned, state the following:

- I have a chemical education from HTI in Brugge, Belgium that is equivalent to a bachelor's degree.
- I have been employed in the polyurethanes industry since 1987 and have worked with Huntsman since 1999; my current title is Research Scientist.
- 3. I have read US Patent 5,399,310, issued to Payne et al. (hereinafter "Payne" or "the Payne reference").
- 4. To demonstrate the effect that the Payne reference's mould release technique has on a flexible polyurethane foam moulding process, I prepared a release agent according to Payne's instructions at column 4, line 60-column 5, line 42 by adding, at ambient temperature, 5.2 g of a 10 % lithium hydroxide solution (aqueous) to 188.6 g of deionised water. With stirring, 6.0 g of Pripol 1004 dimer acid was slowly added to the solution and the pH of the solution was adjusted by the drop-wise addition of additional LiOH (0.4g) to give a clear, colourless solution with the lowest pH possible. To the resulting solution 0.2g Aerosol OT 75% was added and stirring was continued for 15 minutes. The solution was further diluted with 200 g of deionised water.
- 5. This mould release agent was used by my colleague Herman Eugene Germain Moureau to produce flexible polyurethane foams.

I declare that all statements made of my own knowledge are true, and that all statement made on information and belief are believed to be true. I made these statements with the knowledge that wilful false statements and the like are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and may jeopardize the validity of the application or any patent issued thereon.

Date 215t, 2003

Hans Godelieve Guido Verbeke